

KPFA-3010RGBC-11

3.0 x 1.0 mm Right Angle SMD Chip LED Lamp



DESCRIPTIONS

- . The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode
- The Blue source color devices are made with InGaN Light Emitting Diode
- · Electrostatic discharge and power surge could damage the LEDs
- · It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

FEATURES

- 3.0 x 1.5 x 1.0 mm right angle SMD LED, 1.0 mm thickness
- · Low power consumption
- Wide viewing angle
- · Ideal for backlight and indicator
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- · Tinned pads for improved solderability
- · RoHS compliant

APPLICATIONS

- Backlight
- Status indicator
- Home and smart appliances
- · Wearable and portable devices
- Healthcare applications

CELECTION CLUDE

ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices



1. All dimensions are in millimeters (inches) Tolerance is ±0.2(0.008") unless otherwise noted

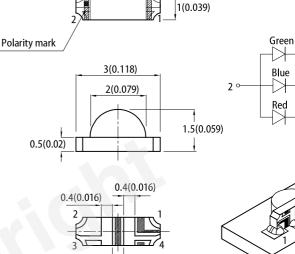
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice

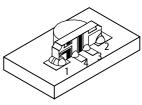
The device has a single mounting surface. The device must be mounted according to the specifications.

Part Number	Emitting Color (Material)	Lens Type	lv (mcd) @ 20mA ^[2]		Viewing Angle ^[1]	
			Min.	Тур.	201/2	
KPFA-3010RGBC-11	Hyper Red (AlGaInP)		80	140		
	Green (InGaN)	Water Clear	300	500	150°	
	Blue (InGaN)		40	70		

Protes:
01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity / luminous flux: +/-15%.
Luminous intensity value is traceable to CIE127-2007 standards.

PACKAGE DIMENSIONS





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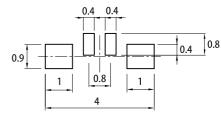
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Blue

Red

RECOMMENDED SOLDERING PATTERN (units : mm; tolerance : ± 0.1)

0.4(0.016)



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ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Denemator	Cumple al	Emitting Color	Value		11
Parameter	Symbol	Emitting Color	Тур.	Max. Uni	
Wavelength at Peak Emission I_F = 20mA	λ _{peak}	Hyper Red Green Blue	630 515 460	-	nm
Dominant Wavelength I_F = 20mA	λ _{dom} ^[1]	Hyper Red Green Blue	621 525 465	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	Hyper Red Green Blue	20 35 25	-	nm
Capacitance	С	Hyper Red Green Blue	25 45 100	-	pF
Forward Voltage I_F = 20mA	V _F ^[2]	Hyper Red Green Blue	2.0 3.3 3.3	2.5 4.1 4.0	V
Reverse Current (V _R = 5V)	I _R	Hyper Red Green Blue	-	10 50 50	μA
Temperature Coefficient of λ_{peak} I_F = 20mA, -10°C \leq T \leq 85°C	ТС _{λреак}	Hyper Red Green Blue	0.13 0.05 0.04	-	nm/°C
Temperature Coefficient of λ_{dom} I_{F} = 20mA, -10°C \leq T \leq 85°C	TC _{λdom}	Hyper Red Green Blue	0.06 0.03 0.03	-	nm/°C
Temperature Coefficient of V_F I _F = 20mA, -10°C \leq T \leq 85°C	TCv	Hyper Red Green Blue	-1.9 -3 -3	-	mV/°C

Notes:

1. The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance $\lambda d: \pm 1$ nm.)

Forward voltage: ±0.1V.
Wavelength value is traceable to CIE127-2007 standards.
Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

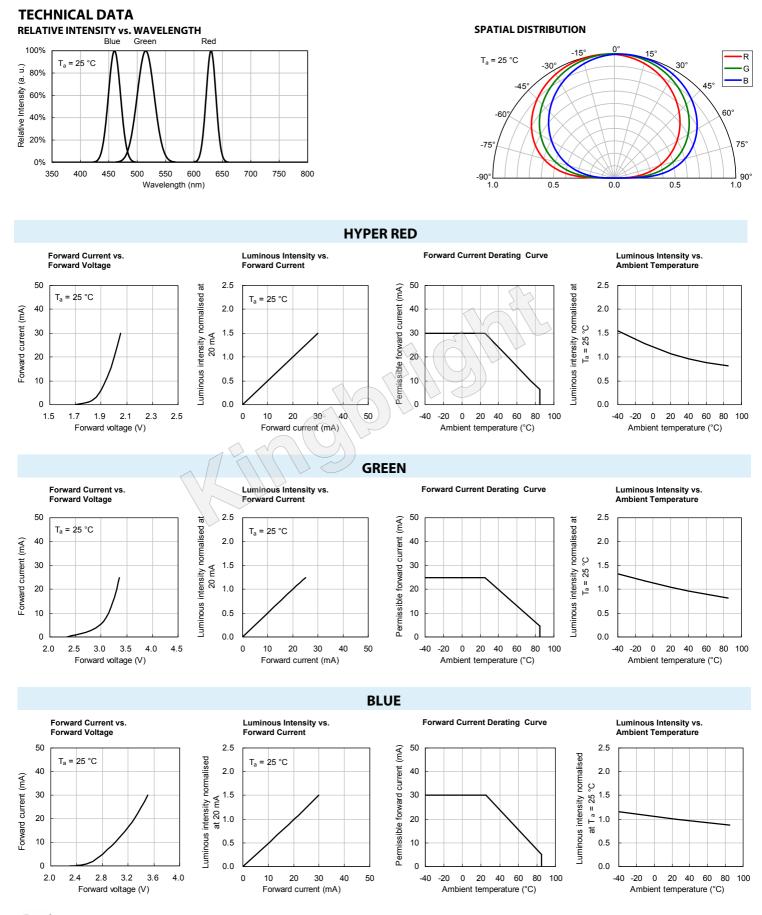
	Symbol	Value			11-14
Parameter		Hyper Red	Green	Blue	Unit
Power Dissipation	PD	75	102.5	120	mW
Reverse Voltage	V _R	5	5	5	V
Junction Temperature	Tj	115	115	115	°C
Operating Temperature	T _{op}	-40 to +85			°C
Storage Temperature	T _{stg}	-40 to +85			°C
DC Forward Current	IF	30	25	30	mA
Peak Forward Current	I _{FM} ^[1]	195	150	150	mA
Electrostatic Discharge Threshold (HBM)	-	3000	450	250	V
Thermal Resistance (Junction / Ambient)	$R_{th JA}^{[2]}$	405	650	620	°C/W
Thermal Resistance (Junction / Solder point)	$R_{th\;JS}^{[2]}$	275	560	535	°C/W

Notes:

Noies. 1. 1/10 Duty Cycle, 0.1ms Pulse Width. 2. R_{th JA}, R_{th JS} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad). 3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

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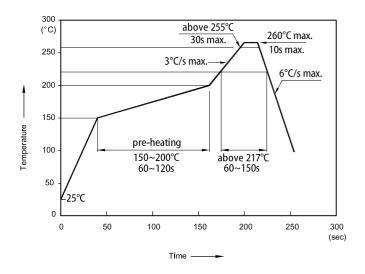


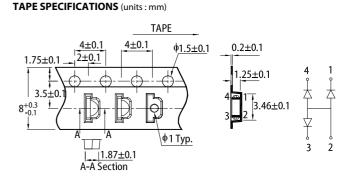
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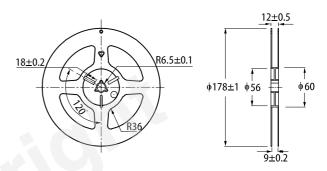
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REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS





REEL DIMENSION (units : mm)

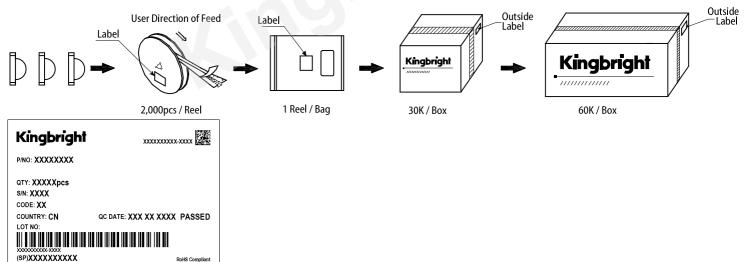


Notes

Don't cause stress to the LEDs while it is exposed to high temperature

 The maximum number of reflow soldering passes is 2 times.
Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications. 2
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